

IN THE SPECIFICATION

Please replace the paragraph on page 7, lines 17-32 with the following paragraph:

A1 As illustrated in Figure 2, each of the processing apparatus 16 typically includes a body 18 that defines a cavity 20. The body typically has at least one conduit 22 for delivering a gas, creating a vacuum, delivering electrical energy to the cavity, or the like. As the processing apparatus 16 moves adjacent the substrate 14, some processing apparatuses can contact the support 12, the substrate 14 and/or a platform 24 (Figure 1) to provide a seal around the target portion of the substrate 14. Thereafter, if desired, a vacuum can be created around the target portion of the substrate 14 prior to a delivery of a metal onto the substrate. The cavity 20 typically will have a volume of approximately 16,000 in<sup>3</sup>. In contrast, standard vacuum chambers will have a total volume of almost 300,000 in<sup>3</sup>. Because the cavity has a smaller volume than conventional vacuum chambers, a vacuum can be created quicker and the processing of the substrate can be completed faster. It should be appreciated however, that the size of the body 18 and cavity 20 can be varied to allow for different sized substrates and different processing speeds. Additionally, not all processes of the present invention require a creation of a vacuum. For example, if the processing apparatus 16 is used to shape the substrate the body 18, the processing apparatus may not have a cavity and a vacuum may not be created around the substrate.